

Amendments to the Specification

Please replace the paragraph beginning at page 11, line 21, with the following rewritten paragraph:

Accelerators reduce cathodic polarization and compete with ~~suppressers~~suppressors for adsorption sites to accelerate copper growth in the adsorbed areas. The accelerators used in the plating composition may include, e.g., sulphur containing compounds, such as bis(sodium sulfopropyl)disulfide (SPS). Accelerators, with smaller molecular dimensions can diffuse faster than suppressors. For example, CUBATH ViaForm Accelerator (DF74) available from Enthone or Shipley B-3100 accelerator (available from Shipley), may be used. Embodiments of the electroplating compositions may include, for example, an accelerator such as the CUBATH ViaForm DF74. Such an accelerator may be used in any suitable concentration of from about 2 ml/L to about 30 ml/L, from about 2 to about 8 ml/L. For example, about 5 ml/L may be used in an electroplating composition comprising about 50 g/L copper and about 80 g/L sulfuric acid. For seed layers with superior coverage such as CVD, about 8 ml/L of this accelerator may be used. For seed layers with poor bottom coverage (e.g., bottom voids), about 2 ml/L of the DF74 or a like accelerator may be used. In another embodiment, about 10 ml/L of Shipley B-3100 accelerator (available from Shipley) is used in an electroplating composition comprising about 40 g/L copper and about 100 g/L sulfuric acid.

Please replace the paragraph beginning at page 14, line 1, with the following rewritten paragraph:

The contact assembly 160 may include a carrier 162, a plurality of contacts 164 carried by the carrier 162, and a plurality of shafts 166 extending between the carrier 162 and the rotor 142. The contacts 164 can be ring-type spring contacts or other types of contacts that are configured to engage a portion of the seed-layer on the workpiece 101. Commercially available support members 140 and contact assemblies 160 can be used. Particular suitable support members 140 and contact assemblies 160 are disclosed in U.S. Patent Nos. 6,228,232 and 6,080,691 and in U.S. Application Nos. 09/385,784 filed on August 30, 1999 and now US Patent No. 6,280,583; 09/386,803 filed on August 31, 1999 and now US Patent No. 6,309,520; 09/386,610 filed on August 31, 1999 and now US Patent No. 6,309,524; 09/386,197 filed on

August 31, 1999 and now US Patent No. 6,303,010; 09/501,002 filed on February 9, 2000 and now US Patent No. 6,471,913; 09/733,608 filed on December 8, 2000 and now US Patent No. 6,780,374; and 09/804,696 filed on March 12, 2001 and now US Patent No. 6,569,297, all of which are herein incorporated by reference.